

Product / Package Information

Package	SOIC_N
Body Size	150 mils
LeadCount	8
Terminal Finish	100Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.58 E-02	86.20	862000	50.27	502730
Thermosets	Epoxy resin	Proprietary	3.12 E-03	7.50	75000	4.37	43741
Thermosets	Phenol Novolac	9003-35-4	1.66 E-03	4.00	40000	2.33	23329
Other inorganic materials	Antimony Trioxide	1309-64-4	6.23 E-04	1.50	15000	0.87	8748
Thermosets	Brominated Resin	40039-93-8	2.08 E-04	0.50	5000	0.29	2916
Other inorganic materials	Carbon Black	1333-86-4	1.25 E-04	0.30	3000	0.17	1750
Subtotal			4.15 E-02	100	1000000	58.32	583214

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.50	975000	32.88	328762
Copper & its alloys	Iron	7439-89-6	5.64 E-04	2.35	23500	0.79	7924
Copper & its alloys	Zinc	7440-66-6	2.88 E-05	0.12	1200	0.04	405
Copper & its alloys	Phosphorus	7723-14-0	7.21 E-06	0.03	300	0.01	101
Subtotal			2.40 E-02	100.00	1000000	33.72	337192

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.43 E-04	100.0	1000000	0.34	3406

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
In & its alloys	In	7440-31-5	1.37 E-03	100.0	1000000	1.82	18186

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold		3.00 E-04	99.99	1000000	0.42	4212

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon		2.63 E-03	100.0	1000000	3.69	36925

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.04 E-04	90	800000	1.27	12692
Thermosets	Epoxy Resin	Proprietary	1.70 E-04	15	150000	0.24	2380
Others	Curing agent & hardener	Proprietary	5.65 E-05	5	50000	0.08	793
Subtotal			1.13 E-03	100	1000000	1.59	15865

Package Totals	Weight (g)	Percentage (%)	PPM
	7.12 E-02	100.00	1000000

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ADI Proprietary



Product / Package Information	
Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	NiPdAu

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.09 E-02	87.7	877000	47.10	470965
Thermosets	Epoxy Resin	Proprietary	2.33 E-03	5.0	50000	2.69	26851
Thermosets	Phenol Resin	Proprietary	2.33 E-03	5.0	50000	2.69	26851
Thermosets	Epoxy Cresol Novolac	29690-82-2	9.33 E-04	2.0	20000	1.07	10740
Other inorganic materials	Carbon Black	1333-86-3	1.40 E-04	0.3	3000	0.16	1611
Subtotal			4.66 E-02	100.0	1000000	54	537018

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.34 E-02	97.5	975000	38.41	384050
Copper & its alloys	Iron	7439-89-6	8.04 E-04	2.35	23500	0.93	9257
Copper & its alloys	Zinc	7440-66-6	4.11 E-05	0.12	1200	0.05	473
Copper & its alloys	Phosphorus	7723-14-0	1.03 E-05	0.03	300	0.01	118
Subtotal			3.42 E-02	100	1000000	39	393898

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	6.23 E-04	97.27	972697	0.72	7168
Precious metals	Palladium	7440-05-3	1.45 E-05	2.26	22621	0.02	167
Precious metals	Gold	7440-57-5	3.00 E-06	0.47	4683	0.00	35
Subtotal			6.40 E-04	100.00	1000000	0.74	7369

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.20 E-04	99.99	1000000	0.25	2533

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.96 E-03	100	1000000	4.56	45596

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.17 E-04	77.71	777100	1.06	10558
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Butyrolactone, gamma-	96-48-0	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.67 E-05	3.11	31100	0.04	423
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Organosilane	TS ref# 10001	3.67 E-05	3.11	31100	0.04	423
Other inorganic materials	Copper(II) oxide	1317-38-0	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Epoxy resin modifier	TS ref# 10038	6.14 E-06	0.52	5200	0.007	71
Subtotal			1.18 E-03	100	1000000	1.36	13587

Package Totals	Weight (g)	Percentage (%)	PPM
	8.69 E-02	100	1000000

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Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.35 E-02	80.7	807000	47.06	470648
Thermosets	Epoxy resin	Proprietary	4.15 E-03	10.0	100000	5.83	58321
Thermosets	Phenol Novolac	9003-35-4	1.25 E-03	3.0	30000	1.75	17496
Thermosets	Brominated Resin	68541-56-0	1.04 E-03	2.5	25000	1.46	14580
Other inorganic materials	Antimony Trioxide	1309-64-4	8.31 E-04	2.0	20000	1.17	11664
Thermosets	Phenol resin	Proprietary	6.23 E-04	1.5	15000	0.87	8748
Other inorganic materials	Carbon Black	1333-86-4	1.25 E-04	0.3	3000	0.17	1750
Subtotal			4.15 E-02	100.0	1000000	58.32	583208

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.57	975706	32.90	329007
Copper & its alloys	Iron	7439-89-6	5.47 E-04	2.28	22789	0.77	7684
Copper & its alloys	Zinc	7440-66-6	3.03 E-05	0.13	1263	0.04	426
Copper & its alloys	Phosphorus	7723-14-0	5.82 E-06	0.02	242	0.01	82
Subtotal			2.40 E-02	100.00	1000000	33.72	337199

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.43 E-04	100.0	1000000	0.34	3406

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.16 E-03	85.0	850000	1.63	16308
Tin & its alloys	Lead	7439-92-1	2.05 E-04	15.0	150000	0.29	2878
Subtotal			1.37 E-03	100.0	1000000	1.92	19186

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.00 E-04	99.99	1000000	0.42	4212

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	3.69	36925

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.78 E-04	77.71	777100	1.23	12329
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Butyrolactone, gamma-	96-48-0	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.51 E-05	3.11	31100	0.05	493
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Organosilane	TS ref# 10001	3.51 E-05	3.11	31100	0.05	493
Other inorganic materials	Copper(II) oxide	1317-38-0	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Epoxy resin modifier	TS ref# 10038	5.88 E-06	0.52	5200	0.01	82
Subtotal			1.13 E-03	100.00	1000000	1.59	15865

Package Totals	Weight (g)	Percentage (%)	PPM
	7.12 E-02	100.00	1000000

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